#### Supplier Name: Contact Info: Form/Declaration Type: Created on

# Texas Instruments Inc. (DUNS# 00-732-1904) ti.com/support Distribute - RoHS and IEC 62474 DB

05/30/2022

# Details for "INA211BQDCKRQ1"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
INA211BQDCKRQ1	NIPDAU	Level-2-260C-1 YEAR	Ext-Mfg	DCK   6	2x1.3x0.9	7.1

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information** 

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

## **Component Information**

				Homoge	eneous Material Level	Component Level				
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm			
Bond Wire										
Precious Metals	Gold	7440-57-5	0.0223	100	1000000	0.312271	3123			
Sub-Total			0.0223	100	1000000	0.312271	3123			
Die Attach Adhesive										
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.021294	30	300000	0.298184	2982			
Other Inorganic Materials	Silica	7631-86-9	0.003194	4.499859	44999	0.044726	447			
Other Organic Materials	Chlorine	7782-50-5	0.000025	0.035221	352	0.00035	4			
Thermoplastics	Ероху	85954-11-6	0.046467	65.46492	654649	0.650685	6507			
Sub-Total			0.07098	100	1000000	0.993945	9939			
Lead Frame										
Copper and Its Alloys	Copper	7440-50-8	2.923125	97.4375	974375	40.933023	409330			
Copper and Its Alloys	Iron	7439-89-6	0.0705	2.35	23500	0.987224	9872			
Copper and Its Alloys	Phosphorus	7723-14-0	0.002475	0.0825	825	0.034658	347			
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00015	0.005	50	0.0021	21			
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00375	0.125	1250	0.052512	525			
Sub-Total			3	100	1000000	42.009517	420095			
Lead Frame Plating										
Nickel and Its Alloys	Nickel	7440-02-0	0.09512	95.12	951200	1.331982	13320			
Precious Metals	Gold	7440-57-5	0.00078	0.78	7800	0.010922	109			
Precious Metals	Palladium	7440-05-3	0.0041	4.1	41000	0.057413	574			
Sub-Total			0.1	100	1000000	1.400317	14003			
Mold Compound										
Other Inorganic Materials	Fused Silica	60676-86-0	3.278141	93.249992	932500	45.904373	459044			
Other Plastics and Rubber	Carbon Black	1333-86-4	0.008789	0.250012	2500	0.123074	1231			
Thermoplastics	Epoxy	85954-11-6	0.228503	6.499996	65000	3.199767	31998			
Sub-Total			3.515433	100	1000000	49.227214	492272			
Semiconductor Device										
Ceramics / Glass	Doped Silicon	7440-21-3	0.432526	100	1000000	6.056736	60567			
Sub-Total			0.432526	100	1000000	6.056736	60567			
Total			7.141239			100	1000000			

#### Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component. See Glossary of Terms for more details.

#### Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

## Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

### Material Declaration Certificate for Semiconductor IC Packaged Products

To certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

#### Important Information/Disclaime

Ti bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. Ti and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

#### Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Pavne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/30/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.